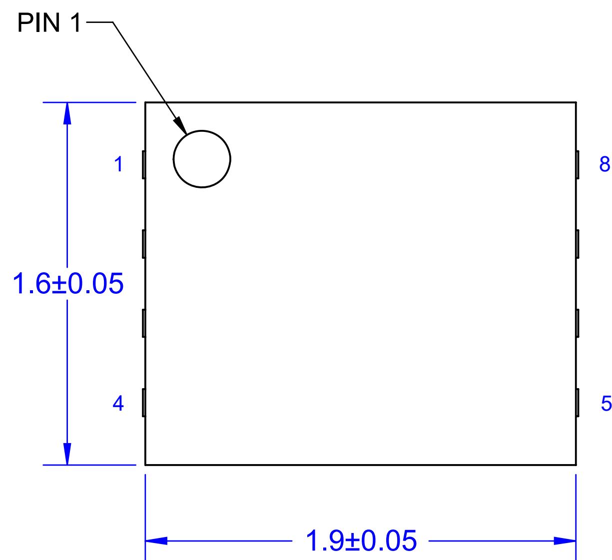
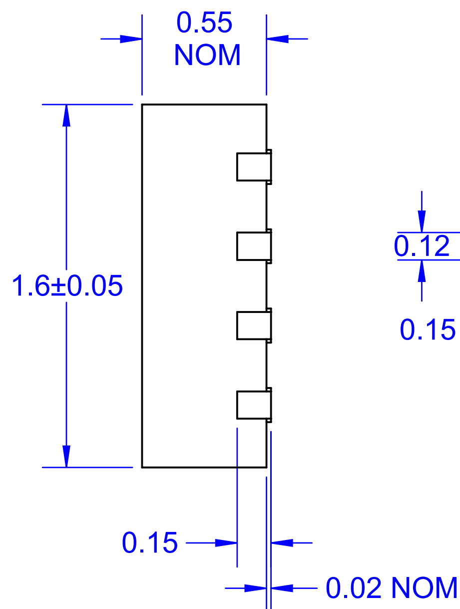
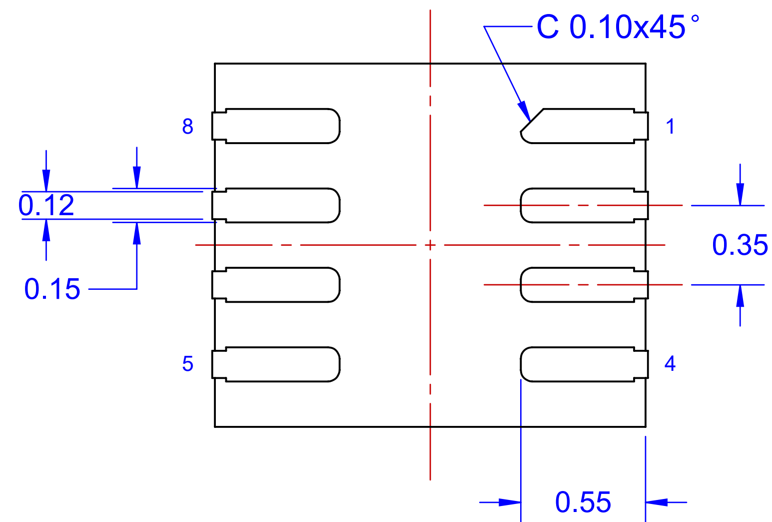
TOP VIEW



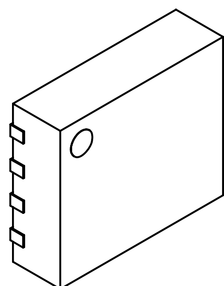
SIDE VIEW



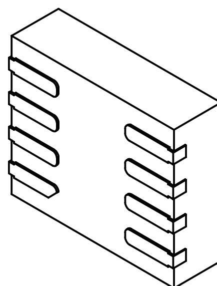
BOTTOM VIEW



MODEL



TOP



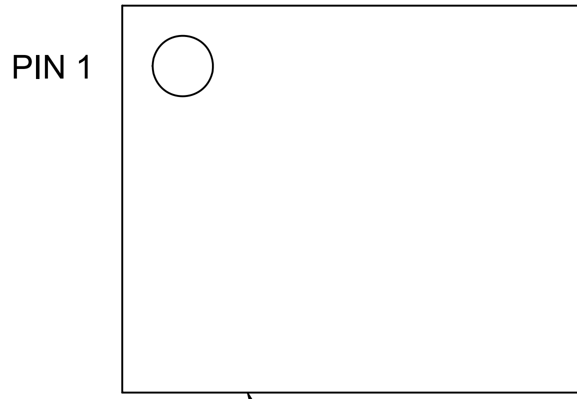
BOTTOM

Notes: (Unless Otherwise Specified).
1) BODY: PLASTIC, SEMICONDUCTOR GRADE.
2) LEAD FRAME: COPPER, C-194 F/H.
3) LEAD FRAME PLATING: NiPdAu.
4) FRAME THICKNESS: 0.15mm.
5) DIE PAD: NOT EXPOSED.
6) JEDEC OUTLINE: MO-220.
7) DIMENSIONS IN mm.

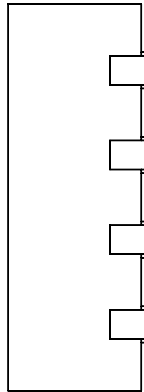
APPROVALS		DATE	TopLine®			
DRAWN	T.Au	7/13/2023				
ENG	M. Hart	7/13/2023	TITLE 8-LEAD 1.6x1.9mm P=0.35mm DFN DAISY CHAIN			
MFG						
QA			SCALE 15:1	SIZE A	DRAWING NO. 430840	REV A
CUST						
REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 5	

DAISY CHAIN PATTERN

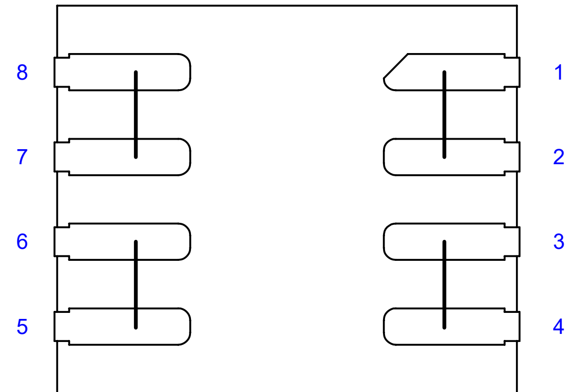
TOP VIEW



SIDE VIEW



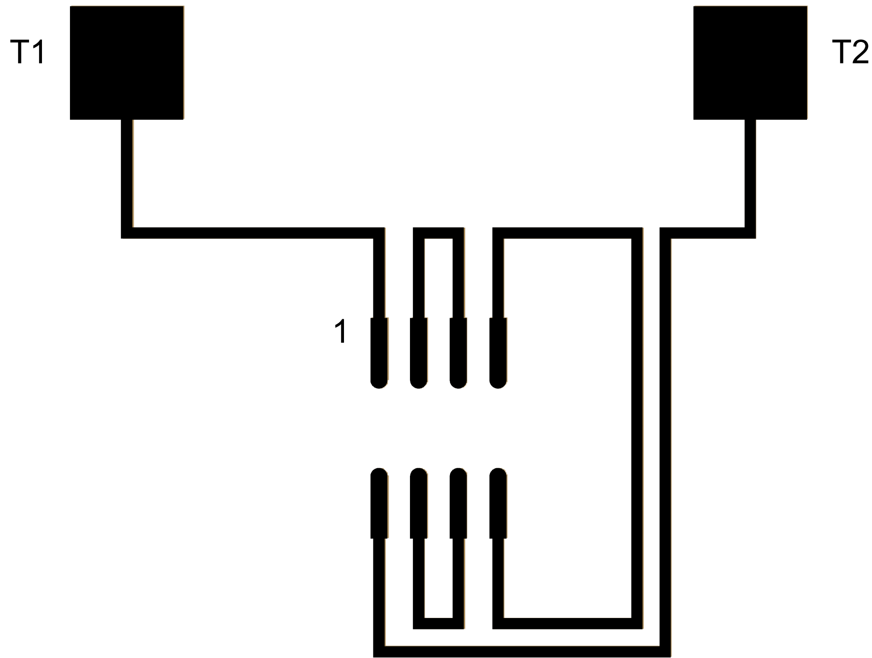
BOTTOM VIEW



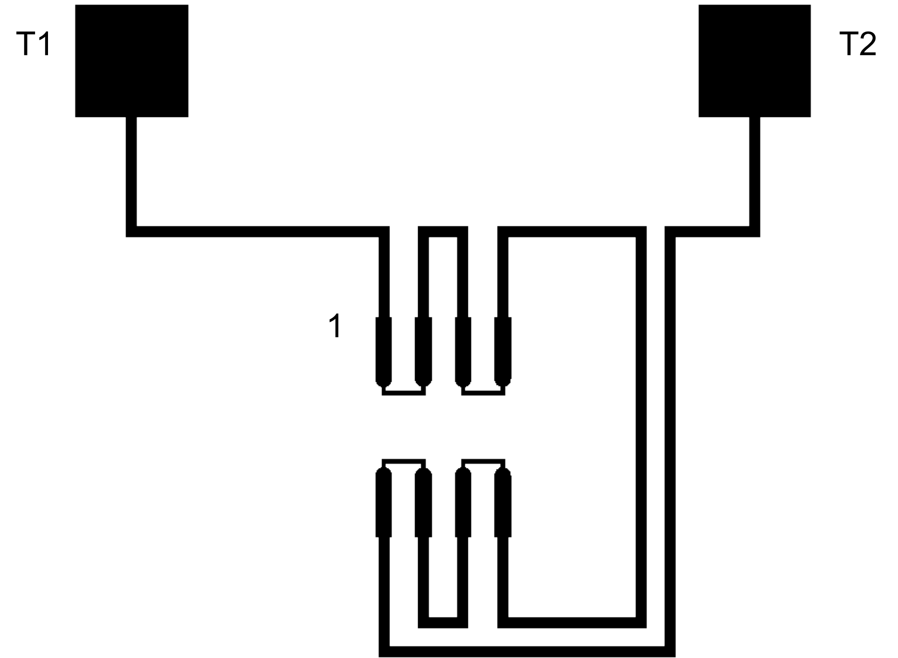
NOTE:
1. PACKAGE DAISY CHAIN BY WIRE BONDING TO INTERNAL BOND PADS.

TopLine®

TITLE	8-LEAD 1.6x1.9mm P=0.35mm DFN DAISY CHAIN		
SCALE	SIZE	DRAWING NO.	REV
16:1	A	430840	A
DO NOT SCALE DRAWING		SHEET 2 OF 5	

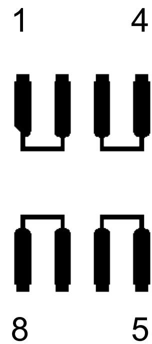


RECOMMENDED
PCB PADS



AFTER MOUNTING
ON PCB

1 4

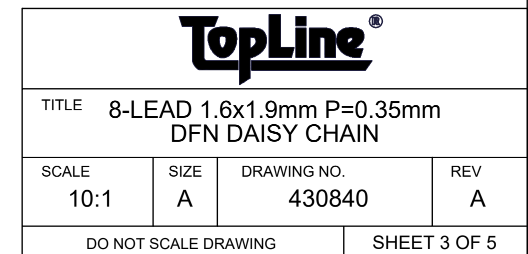


8 5

DFN

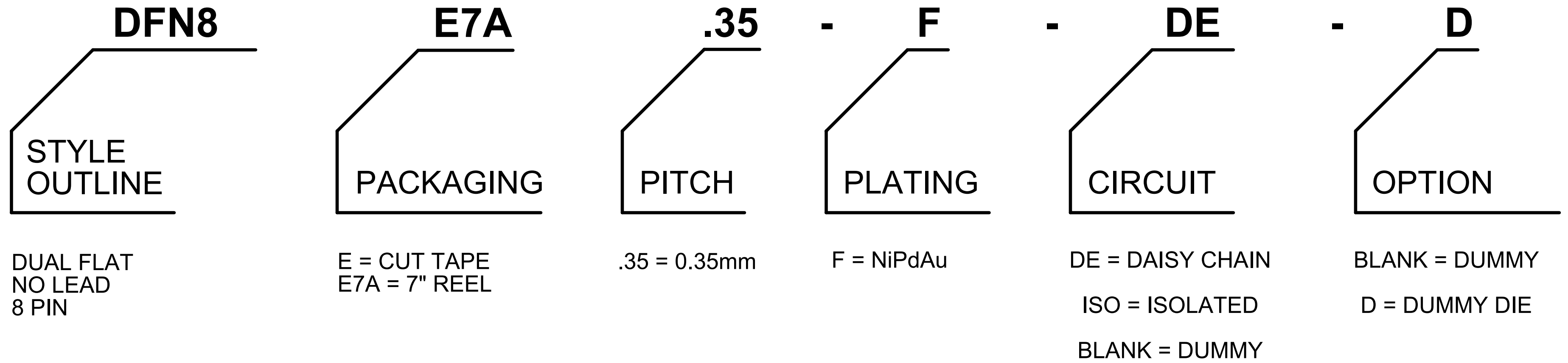
DAISY CHAIN NET LIST

PINS	PINS
1 ~ 2	3 ~ 4
5 ~ 6	7 ~ 8



TITLE	8-LEAD 1.6x1.9mm P=0.35mm DFN DAISY CHAIN		
SCALE 10:1	SIZE A	DRAWING NO. 430840	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 5	

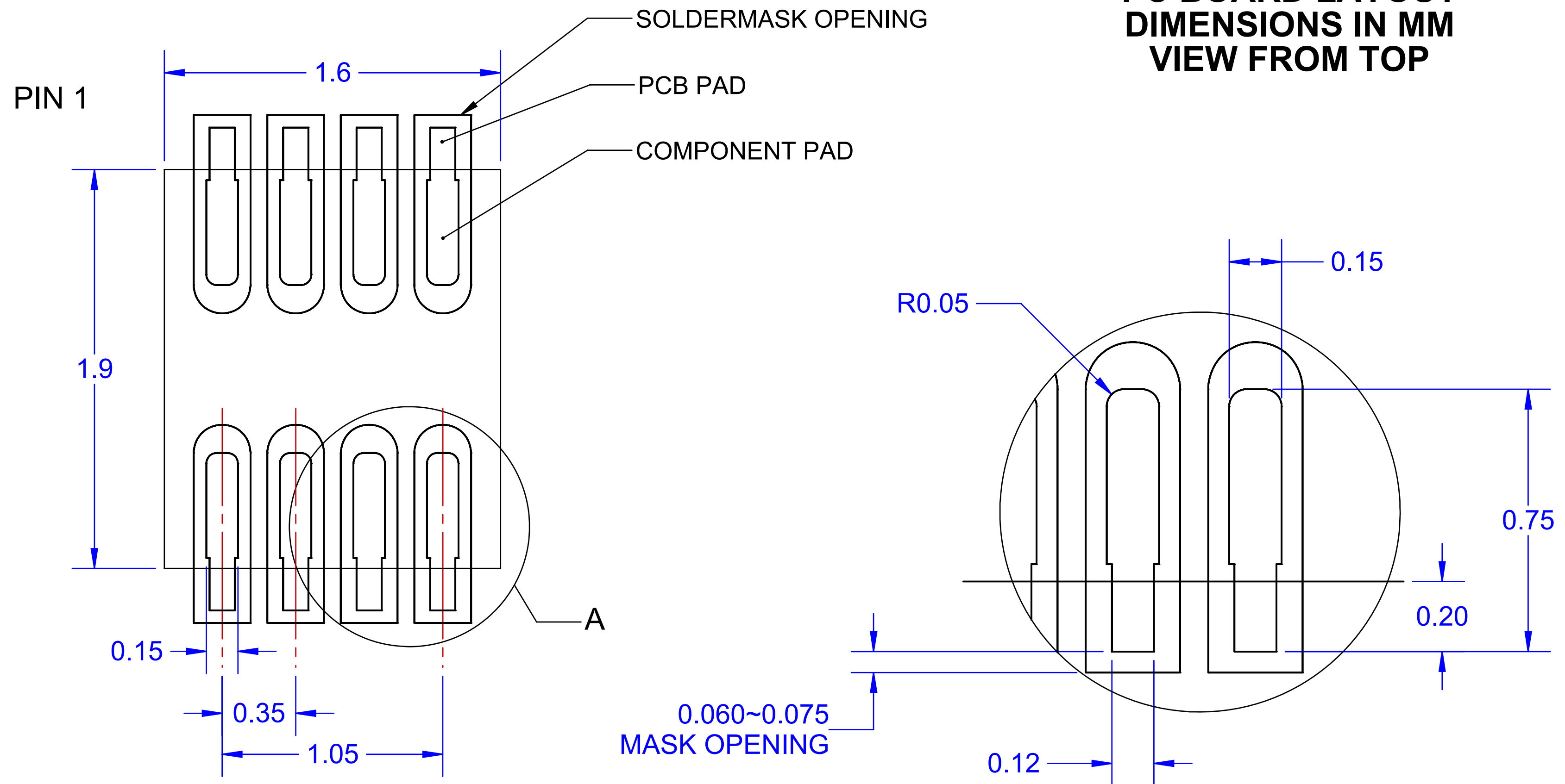
PART NUMBERING SYSTEM



PART NUMBER	DAISY CHAIN	PACKAGING	RoHS Pb-FREE	DUMMY DIE
DFN8E7A.35-F-DE-D	YES	REEL	YES	YES
DFN8E.35-F-DE-D	YES	CUT TAPE	YES	YES

OTHER PART NUMBER COMBINATIONS AVAILABLE. CONTACT TOPLINE.

TopLine®			
TITLE: 8-LEAD 1.6x1.9mm P=0.35mm DFN DAISY CHAIN			
SCALE: NONE	SIZE: A	DRAWING NO.: 430840	REV: A
DO NOT SCALE DRAWING		SHEET 4 OF 5	



Notes: (Unless Otherwise Specified).
1) DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
2) SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (NSMD) SOLDER MASK OPENING (2.4~3.0mils) OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
3) ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
4) PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
5) THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
6) REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
7) THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
   A) MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
   B) DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
   C) PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18µm).
   D) TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
8) STENCIL DESIGN MAY BE CHANGED TO SUIT REQUIREMENTS OF THE DESIGNER.
   A) LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
   B) THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERATURES INSTEAD OF ONE LARGE APERATURE TO CONTROL PASTE AMOUNTS.
   C) APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.

DETAIL A
SCALE 50 : 1

TopLine®

TITLE	8-LEAD 1.6x1.9mm P=0.35mm DFN DAISY CHAIN		
SCALE	SIZE	DRAWING NO.	REV
18:1	A	430840	A
DO NOT SCALE DRAWING		SHEET 5 OF 5	